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TITLE : WIRE FOR BUILD-UP WELDING OF BEARING METAL

ABSTRACT : PURPOSE: To prevent high-temp. crack and defective adhesion by constituting a wire of the compns. which contains specific weight % each of Sb, Pb, Cd, Fe, Zn and Cu and composed of the balance Sn and incidental impurities.

CONSTITUTION: The wire is composed of the compsn. contg. 8.0~10.0% Sb, 5.0~6.0% Cu, $\leq 0.1\%$ Pb, $\leq 0.05\%$ Cd, $\leq 0.02\%$ Fe and $\leq 0.01\%$ Zn and consisting of the balance Sn and impurities. The components Pb, Cd and Fe are controlled respectively $\leq 0.1\%$, $\leq 0.05\%$ and $\leq 0.02\%$ and therefore the generation of the high-temp. crack and harmful defects on solidifying of a white metal is obviated if such wire is used to make lining by TIG welding. The adhesiveness to a backing metal is thus improved.

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